



MILLIMETER DIMENSIONS ARE DERIVED FROM ORIGINAL INCH DIMENSIONS

SYMBOL	INCH MIN.	ES MAX.	MILLI MIN.	METERS MAX.	NOTES
ABBOE e e L LP	.090 .025 .015 .400 .280 .080 .160 .595 .100 .130	.120 .035 .025 .450 .330 .100 .200 .655 .100 .130	2.29 .64 .39 10.16 7.12 2.04 4.07 15.12 - 2.54 3.31	3.04 .88 .63 11.43 8.38 2.54 5.08 16.63 2.54 3.30 4.44	- 4 - 3 3 - 1

NOTES:

- 1. LEAD DIMENSIONS NOT CONTROLLED IN THIS ZONE TO ALLOW FOR BODY FLASH AND LEAD FINISH BUILD-UP.
- 2. MAXIMUM RADIUS OF .050 IN. (1.27 MM) ON ALL BODY EDGES AND CORNERS.
- 3. LEAD SPACING TO BE MEASURED BETWEEN .100 IN. (2.54 MM) AND .125 IN. (3.17 MM) FROM THE POINT OF EMERGENCE FROM THE BODY.
- 4. TYPICAL ALL LEADS.

CHANGES: SEE 11.2.F.20 Ltb.

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